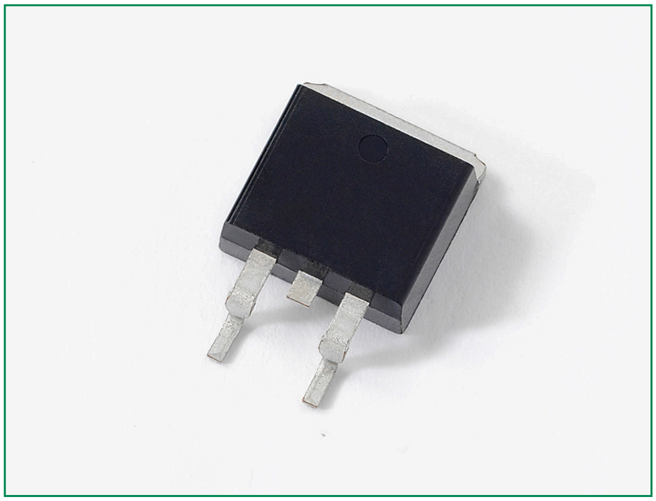
NGB8206AN - 20 A, 350 V, N-Channel Ignition IGBT, D²PAK



20 Amps, 350 Volts
$V_{CE}(on) \leq 1.3$ V @
$I_C = 10A$, $V_{GE} \geq 4.5$ V

Description

This Logic Level Insulated Gate Bipolar Transistor (IGBT) features monolithic circuitry integrating ESD and Over–Voltage clamped protection for use in inductive coil drivers applications. Primary uses include Ignition, Direct Fuel Injection, or wherever high voltage and high current switching is required.

Features

- Ideal for Coil–on–Plug and Driver–on–Coil Applications
- Gate–Emitter ESD Protection
- Temperature Compensated Gate–Collector Voltage Clamp Limits Stress Applied to Load
- Integrated ESD Diode Protection
- Low Threshold Voltage for Interfacing Power Loads to Logic or Microprocessor Devices
- Low Saturation Voltage
- High Pulsed Current Capability
- These are Pb–Free Devices

Applications

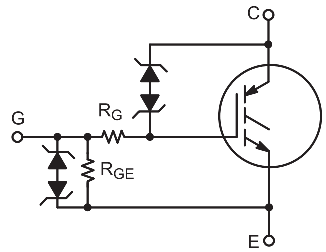
- Ignition Systems

Maximum Ratings (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	V_{CES}	390	V
Collector–Gate Voltage	V_{CER}	390	V
Gate–Emitter Voltage	V_{GE}	±15	V
Collector Current–Continuous @ T_C = 25°C – Pulsed	I_C	20 50	A_{DC} A_{AC}
Continuous Gate Current	I_G	1.0	mA
Transient Gate Current (t ≤ 2 ms, f ≤ 100 Hz)	I_G	20	mA
ESD (Charged–Device Model)	ESD	2.0	kV
ESD (Human Body Model) R = 1500 Ω, C = 100 pF	ESD	8.0	kV
ESD (Machine Model) R = 0 Ω, C = 200 pF	ESD	500	V
Total Power Dissipation @ T_C = 25°C Derate above 25°C	P_D	150 1.0	Watts W/°C
Operating and Storage Temperature Range	T_J, T_{stg}	–55 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Functional Diagram



Additional Information

Datasheet | Resources | Samples

Revised: 02/15/18

Unclamped Collector–To–Emitter Avalanche Characteristics (–55° ≤ T_J ≤ 175°C)

	Symbol	Value	Unit
Single Pulse Collector–to–Emitter Avalanche Energy			
V_{CC} = 50 V, V_{GE} = 5.0 V, P_k I_L = 16.7 A, R_G = 1000 Ω, L = 1.8 mH, Starting T_J = 25°C	E_{AS}	250	mJ
V_{CC} = 50 V, V_{GE} = 5.0 V, P_k I_L = 14.9 A, R_G = 1000 Ω, L = 1.8 mH, Starting T_J = 150°C		200	
V_{CC} = 50 V, V_{GE} = 5.0 V, P_k I_L = 14.1 A, R_G = 1000 Ω, L = 1.8 mH, Starting T_J = 175°C		180	
Reverse Avalanche Energy			
V_{CC} = 100 V, V_{GE} = 20 V, P_k I_L = 25.8 A, L = 6.0 mH, Starting T_J = 25°C	$E_{AS(R)}$	2000	mJ

1. When surface mounted to an FR4 board using the minimum recommended pad size.

Thermal Characteristics

Rating	Symbol	Value	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.0	°C/W
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	62.5	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8″ from case for 5 seconds	T_L	275	°C

Electrical Characteristics - OFF

Characteristic	Symbol	Test Conditions	Temperature	Min	Typ	Max	Unit
Collector–Emitter Clamp Voltage	BV_{CES}	I_C = 2.0 mA	T_J = –40°C to 150°C	325	350	375	V
		I_C = 10 mA	T_J = –40°C to 150°C	340	365	390	
Zero Gate Voltage Collector Current	I_{CES}	V_{CE} = 15 V, V_{GE} = 0 V,	T_J = 25°C	–	0.1	1.0	μA
		V_{CE} = 175V V_{GE} = 0 V	T_J = 25°C	0.5	1.5	10	
			T_J = 175°C	1.0	25	100*	
			T_J = -40°C	0.4	0.8	5.0	
Reverse Collector–Emitter Clamp Voltage	$BV_{CES(R)}$	I_C = –75 mA	T_J = 25°C	30	35	39	V
			T_J = 175°C	32	37	42	
			T_J = –40°C	29	32	37	
Reverse Collector–Emitter Leakage Current	$I_{CES(R)}$	V_{CE} = –24 V	T_J = 25°C	0.05	0.25	1.0	mA
			T_J = 175°C	1.0	12.5	25	
			T_J = –40°C	0.005	0.03	0.25	
Gate–Emitter Clamp Voltage	BV_{GES}	I_G = ±5.0 mA	T_J = –40°C to 175°C	12	12.5	14	V
Gate–Emitter Leakage Current	I_{GES}	V_{GE} = ±5.0 V	T_J = –40°C to 175°C	200	300	350*	μA
Gate Resistor	R_G	-	T_J = –40°C to 175°C	-	-	-	Ω
Gate Emitter Resistor	R_{GE}	-	T_J = –40°C to 175°C	14.25	16	25	kΩ

Electrical Characteristics - ON (Note 3)

Characteristic	Symbol	Test Conditions	Temperature	Min	Typ	Max	Unit
Gate Threshold Voltage	$V_{GE(th)}$	I_C = 1.0 mA, $V_{GE} = V_{CE}$	T_J = 25°C	1.5	1.8	2.1	V
			T_J = 175°C	0.7	1.0	1.3	
			T_J = –40°C	1.7	2.0	2.3*	
Threshold Temperature Coefficient (Negative)	–	–	–	3.8	4.6	6.0	mV/°C

*Maximum Value of Characteristic across Temperature Range.

3. Pulse Test: Pulse Width ≤ 300 μS, Duty Cycle ≤ 2%.

Electrical Characteristics - ON (Note 4)

Characteristic	Symbol	Test Conditions	Temperature	Min	Typ	Max	Unit
Collector−to−Emitter On−Voltage	$V_{CE\ (on)}$	I_C = 6.5 A, V_{GE} = 3.7 V	T_J = 25°C	0.95	1.15	1.35	V
			T_J = 175°C	0.70	0.95	1.15	
			T_J = −40°C	1.0	1.30	1.40	
		I_C = 9.0 A, V_{GE} = 3.9 V	T_J = 25°C	0.95	1.25	1.45	
			T_J = 175°C	0.8	1.05	1.25	
			T_J = −40°C	1.1	1.4	1.50	
		I_C = 7.5 A, V_{GE} = 4.5 V	T_J = 25°C	0.85	1.15	1.4	
			T_J = 175°C	0.7	0.95	1.2	
			T_J = −40°C	1.0	1.3	1.6*	
		I_C = 10 A, V_{GE} = 4.5 V	T_J = 25°C	0.9	1.2	1.6	
			T_J = 175°C	0.8	1.05	1.4	
			T_J = −40°C	1.0	1.2	1.7*	
		I_C = 15 A, V_{GE} = 4.5 V	T_J = 25°C	1.0	1.3	1.7	
			T_J = 175°C	1.0	1.3	1.55	
			T_J = −40°C	1.1	1.35	1.8*	
		I_C = 20 A, V_{GE} = 4.5 V	T_J = 25°C	1.3	1.6	1.9	
			T_J = 175°C	1.2	1.5	1.8	
			T_J = −40°C	1.4	1.75	2.0*	
Forward Transconductance	gfs	V_{CE} = 5.0 V, I_C = 6.0 A	T_J = 25°C	10	18	25	Mhos

*Maximum Value of Characteristic across Temperature Range.

3. Pulse Test: Pulse Width ≤ 300 μS, Duty Cycle ≤ 2%.

Dynamic Characteristics

Characteristic	Symbol	Test Conditions	Temperature	Min	Typ	Max	Unit
Input Capacitance	C_{ISS}	V_{CE} = 25 V f = 10 kHz	T_J = 25°C	1100	1300	1500	pF
Output Capacitance	C_{OSS}			70	80	90	
Transfer Capacitance	C_{RSS}			18	20	22	

Switching Characteristics

Characteristic	Symbol	Test Conditions	Temperature	Min	Typ	Max	Unit
Turn−Off Delay Time (Resistive)	$t_{d\,(off)}$	V_{CC} = 300 V, I_C = 9 A R_G = 1.0 kΩ, R_L = 33 Ω, V_{GE} = 5.0 V	T_J = 25°C	6.0	8.0	10	µSec
			T_J = 175°C	6.0	8.0	10	
Fall Time (Resistive)	t_f		T_J = 25°C	4.0	6.0	8.0	
			T_J = 175°C	8.0	10.5	14	
Turn−Off Delay Time (Inductive)	$t_{d\,(off)}$	V_{CC} = 300 V, I_C = 9 A R_G = 1.0 kΩ, L = 300 µH, V_{GE} = 5.0 V	T_J = 25°C	3.0	5.0	7.0	
			T_J = 175°C	5.0	7.0	9.0	
Fall Time (Inductive)	t_f		T_J = 25°C	1.5	3.0	4.5	
			T_J = 175°C	5.0	7.0	10	
Turn−On Delay Time	$t_{d\,(on)}$	V_{CC} = 14 V, I_C = 9.0 A R_G = 1.0 kΩ, R_L = 1.5 Ω, V_{GE} = 5.0 V	T_J = 25°C	1.0	1.5	2.0	
			T_J = 175°C	1.0	1.5	2.0	
Rise Time	t_r		T_J = 25°C	4.0	6.0	8.0	
			T_J = 175°C	3.0	5.0	7.0	

2. Pulse Test: Pulse Width ≤ 300 µS, Duty Cycle ≤ 2%.

*Maximum Value of Characteristic across Temperature Range.

Ratings and Characteristic Curves

Figure 1. Self Clamped Inductive Switching

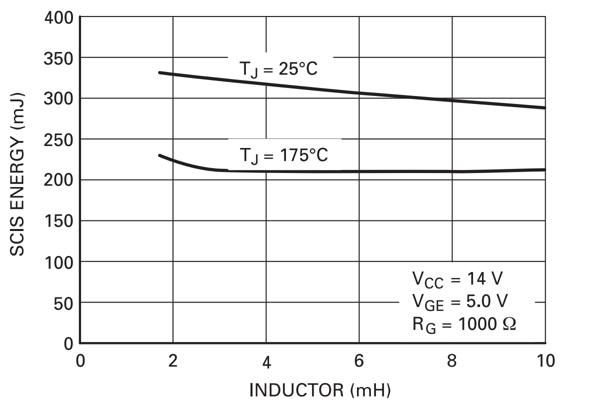


Figure 2. Open Secondary Avalanche Current vs. Temperature

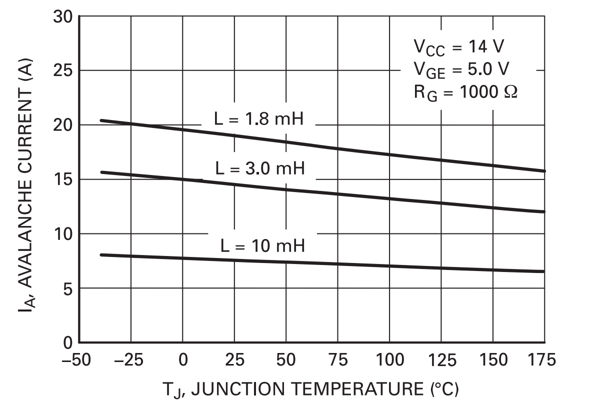


Figure 3. Collector–to–Emitter Voltage vs. Junction Temperature

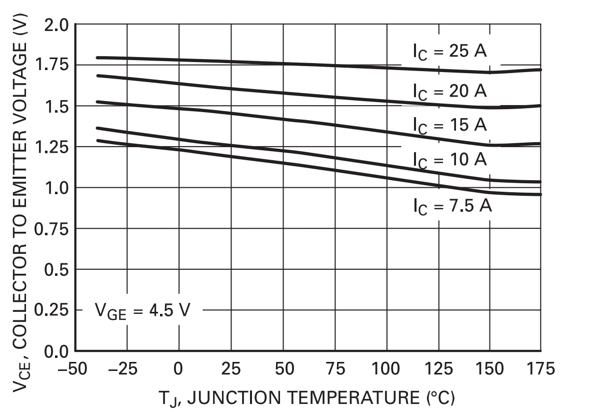


Figure 4. Collector Current vs. Collector–to–Emitter Voltage

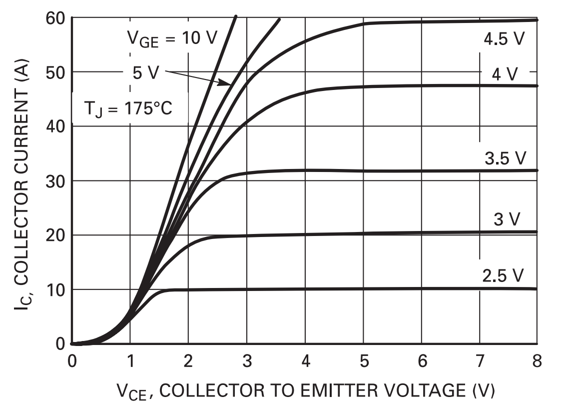


Figure 5. Collector Current vs. Collector–to–Emitter Voltage

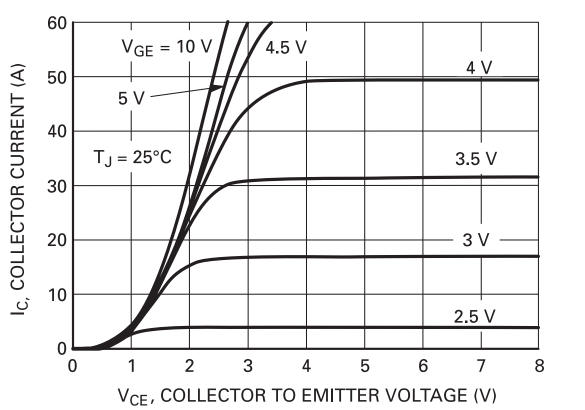


Figure 6. Collector Current vs. Collector–to–Emitter Voltage

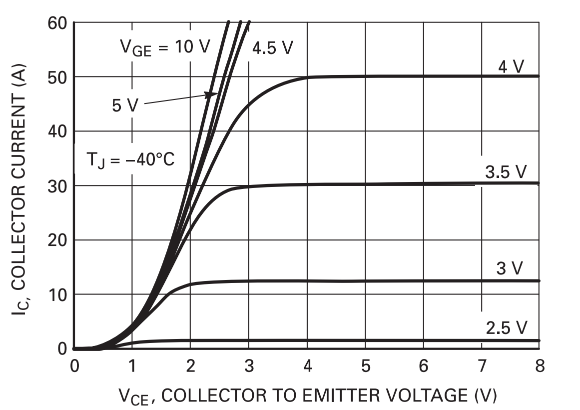


Figure 7. Transfer Characteristics

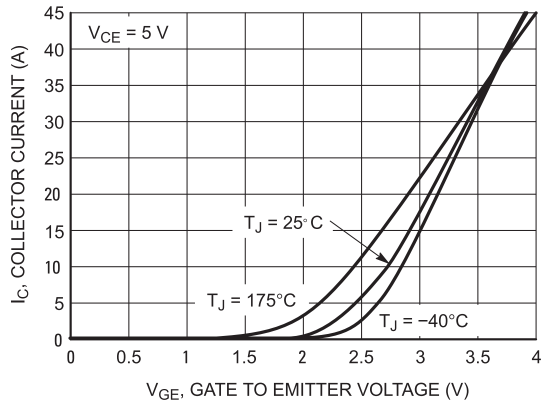


Figure 8. Collector–to–Emitter Leakage Current vs. Temperature

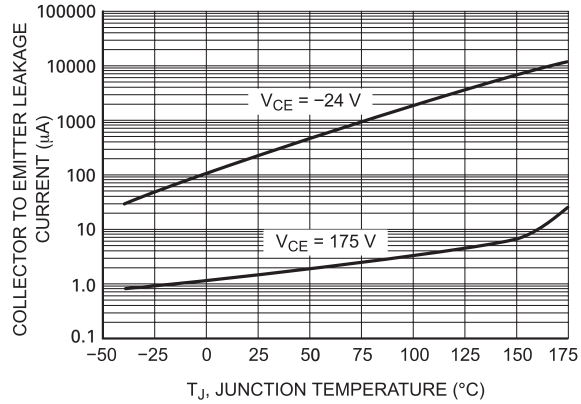


Figure 9. Gate Threshold Voltage vs. Temperature

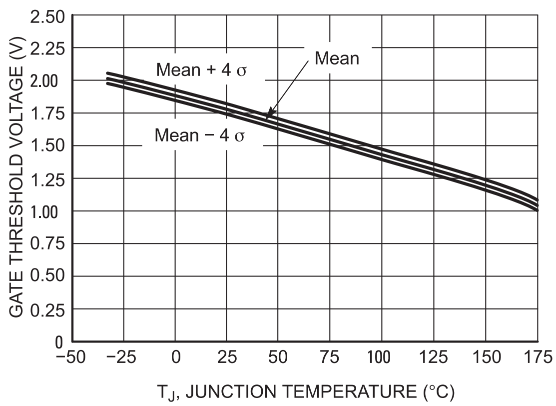


Figure 10. Capacitance vs. Collector–to–Emitter Voltage

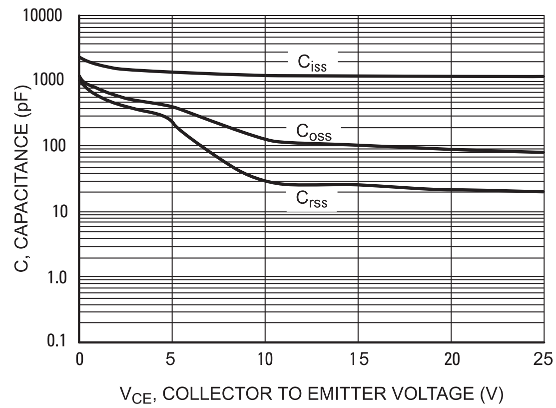


Figure 11. Resistive Switching Fall Time vs. Temperature

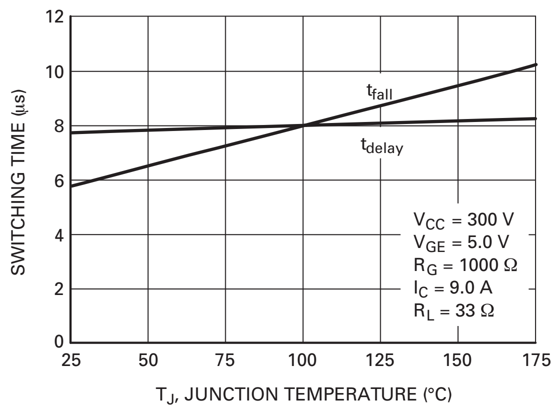


Figure 12. Inductive Switching Fall Time vs. Temperature

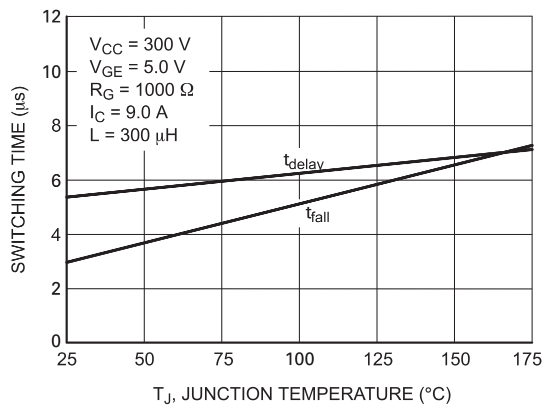
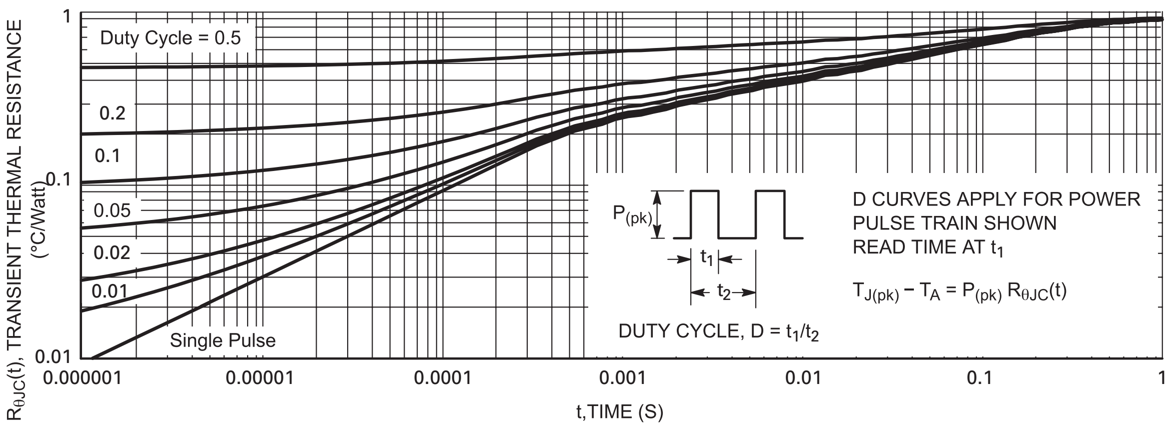
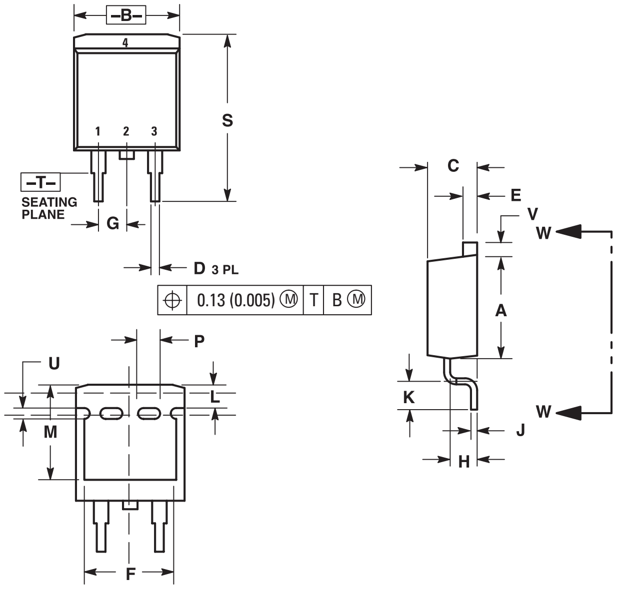


Figure 13. Minimum Pad Transient Thermal Resistance (Non–normalized Junction–to–Ambient)



Dimensions

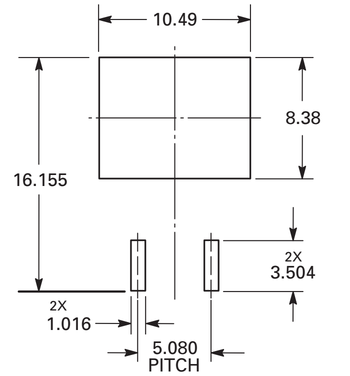


VIEW W–W

Dim	Inches		Millimeters	
	Min	Max	Min	Max
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

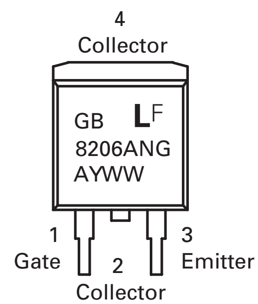
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B–01 THRU 418B–03 OBSOLETE, NEW STANDARD 418B–04.

Soldering Footprint



DIMENSIONS: MILLIMETERS

Part Marking System



GB8206AN = Device Code

A= Assembly Location
Y= Year
WW = Work Week
G = Pb–Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGB8206ANT4G	D^2PAK (Pb–Free)	800 / Tape & Reel
NGB8206ANTF4G	D^2PAK (Pb–Free)	700 / Tape & Reel
NGB8206ANSL3G	D^2PAK (Pb–Free)	50 Units / Rail

LifeElectronics
Живое партнерство

ООО «ЛайфЭлектроникс» "LifeElectronics" LLC

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

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- *Специальные условия для постоянных клиентов.*
- *Подбор аналогов.*
- *Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.*

- *Приемлемые сроки поставки, возможна ускоренная поставка.*
- *Доставку товара в любую точку России и стран СНГ.*
- *Комплексную поставку.*
- *Работу по проектам и поставку образцов.*
- *Формирование склада под заказчика.*

- *Сертификаты соответствия на поставляемую продукцию (по желанию клиента).*
- *Тестирование поставляемой продукции.*
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- *Наличие сертификата ISO.*

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- *Техническую поддержку проекта.*
- *Защиту от снятия компонента с производства.*
- *Оценку стоимости проекта по компонентам.*
- *Изготовление тестовой платы монтаж и пусконаладочные работы.*

Тел: +7 (812) 336 43 04 (многоканальный)
Email: org@lifeelectronics.ru

www.lifeelectronics.ru